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捷多邦, 专业PCB打样工厂, 24小TSM集Q2版TSM102A DUAL OPERATIONAL AMPLIFIER, DUAL COMPARATOR, AND VOLTAGE REFERENCE

SLVS602-MARCH 2006

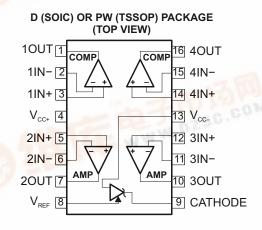
FEATURES

- OPERATIONAL AMPLIFIERS
 - Low Supply Current...200 μA/A
 - Medium Speed...2.1 MHz
 - Low-Level Output Voltage Close to V_{CC-} ...0.1 V Typ (R_L = 10 k Ω)
 - Input Common-Mode Voltage Range Includes Ground
- COMPARATORS
 - Low Supply Current...200 µA/A
 - $(V_{cc} = 5 V)$
 - Input Common-Mode Voltage Range
 Includes Ground
 - Low Output Saturation Voltage...
 Typically 250 mV (I_{sink} = 4 mA)
- VOLTAGE REFERENCE
 - Adjustable Output Voltage...V_{REF} to 36 V
 - Sink Current Capability...1 mA to 100 mA
 - 0.4% (A Grade) and 1% (Standard Grade)
 Precision
 - Latch-Up Immunity

DESCRIPTION/ORDERING INFORMATION

APPLICATIONS

- Switch-Mode Power Supplies
- Battery Chargers
- Voltage and Current Sensing
- Power-Good, Overvoltage, Undervoltage, Overcurrent Detection
- Window Comparators
- Alarms, Detectors, and Sensors



The TSM102 and TMS102A combine the building blocks of a dual operational amplifier, a dual comparator, and a precision voltage reference, all of which often are used to implement a wide variety of power-management functions, including overcurrent detection, undervoltage/overvoltage detection, power-good detection, window comparators, error amplifiers, etc. Additional applications include alarm and detector/sensor applications.

The TSM102A offers a tight V_{REF} tolerance of 0.4% at 25°C. The TSM102 and TSM102A are characterized for operation from -40°C to 85°C.

TA	MAX V _{REF} TOLERANCE (25°C)	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKIN	
		SOIC – D	Tube of 75	TSM102AID	TOMADOAL	
	A grade:	50IC - D	Reel of 2500	TSM102AIDR	TSM102AI	
	0.4% precision	TSSOP – PW	Tube of 90	TSM102AIPW	CNI402AL	
4000 to 0500			Reel of 2000	TSM102AIPWR	- SN102AI	
–40°C to 85°C			Tube of 75	TSM102ID	TSM102I	
	Standard grade:	SOIC – D	Reel of 2500	TSM102IDR	- 151011021	
	1% precision		Tube of 90	TSM102IPW	014001	
	- 87	TSSOP – PW	Reel of 2000	TSM102IPWR	- SN102I	

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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Absolute Maximum Ratings⁽¹⁾

over free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		36	V	
V_{ID}	Input differential voltage		36	V	
VI	Input voltage range	-0.3	36	V	
I _{KA}	Voltage reference cathode current		100	mA	
0	Deckage thermal impedance (2)(3)	(3) D package PW package		73	°C/W
θ_{JA}	Package thermal impedance ⁽²⁾⁽³⁾			108	°C/W
TJ	Maximum junction temperature			150	°C
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) - T_A)/θ_{JA}. Selecting the maximum of 150°C can affect reliability.
 (3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

		MIN	MAX	UNIT
$V_{CC+} - V_{CC-}$	Supply voltage	3	30	V
V _{ID}	Comparator differential input voltage		$V_{CC+} - V_{CC-}$	V
V _{KA}	Cathode-to-anode voltage	V_{REF}	36	V
Ι _K	Reference cathode current	1	100	mA
T _A	Operating free-air temperature	-40	85	°C

Total Device Electrical Characteristics

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
	Total supply current,		25°C		0.8	1.5	س ۸
ICC	excluding reference cathode current	$V_{CC+} = 5 V$, $V_{CC-} = 0 V$, No load	Full range			2	mA



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Operational Amplifier Electrical Characteristics

 V_{CC+} = 5 V, V_{CC-} = GND, R1 connected to $V_{CC}/2$ (unless otherwise noted)

	PARAMETER	TEST CONDITION	IS	T _A	MIN	TYP	MAX	UNIT
V	Input offset voltage			25°C		1	4.5	mV
V _{IO}	input onset voltage			Full range			6.5	IIIV
αV_{IO}	Input offset voltage drift					10		μV/°C
1	Input offset current			25°C		5	20	nA
I _{IO} Input offset current				Full range			40	ΠA
	Input bias current			25°C		20	100	nA
I _{IB}	input bias current			Full range			200	ΠA
٨	Lorgo olgool voltago goin	V _{CC+} = 30 V, R1 = 10 kΩ,		25°C	50	100		N//>/
A _{VD} Large-signal voltage gain		$V_0 = 5 V$ to 25 V						V/mV
k _{SVR}	Supply-voltage rejection ratio	$V_{CC+} = 5 V \text{ to } 30 V$	25°C	80	100		dB	
V	Input common-mode voltage			25°C	V_{CC-}		V _{CC+} – 1.8	v
V _{ICM}	input common-mode voltage			Full range	V_{CC-}		V _{CC+} – 2.2	
CMRR	Common-mode rejection ratio	$V_{CC+} = 30 \text{ V},$ $V_{ICM} = 0 \text{ V to } V_{CC+} - 1.8 \text{ V}$		25°C	70	90		dB
	Short-circuit current	$V_{ID} = \pm 1 V, V_{O} = 2.5 V$	Source	25°C	3	6		~ ^
I _{SC}			Sink		3	6		mA
V	High-level output voltage	$V_{CC+} = 30 \text{ V}, \text{ R}_{L} = 10 \text{ k}\Omega$		25°C	27	28		V
V _{OH}	High-level output voltage			Full range	26			v
M				25°C		130	170	m)/
V _{OL}	Low-level output voltage	$R_{L} = 10 \text{ ksz}$	$R_{L} = 10 \ k\Omega$				200	mV
SR	Slew rate	$\label{eq:V_CC} \begin{array}{l} V_{CC} = \pm 15 \ \text{V}, \ C_L = 100 \ \text{pF}, \\ V_I = \pm 10 \ \text{V}, \ R_L = 10 \ \text{k}\Omega \end{array}$		25°C	1.3	2		V/µs
GBW	Gain bandwidth product	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}, \text{ f} = 100 \text{ kHz}$		25°C	1.4	2.1		MHz
Φm	Phase margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		25°C		45		0
THD	Total harmonic distortion			25°C		0.01		%
V _n	Equivalent input noise voltage	f = 1 kHz		25°C		19		nV/√ Hz



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Comparator Electrical Characteristics

 V_{CC+} = 5 V, V_{CC-} = GND (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT	
V	Input offset voltage		25°C			5	mV	
V _{IO} Input offset voltage			Full range			9	IIIV	
V _{ID}	Comparator differential input voltage		Full range			V _{CC+}	V	
1	Input offect ourrent		25°C			50	nA	
I _{IO}	Input offset current		Full range			150	ΠA	
	Input bias current		25°C			250	nA	
I _{IB}	input bias current		Full range			400	ΠA	
I _{OH} Hig	Lligh lovel output ourrest	N 1 X X 20 X	25°C		0.1		nA	
	High-level output current	$V_{ID} = 1 V, V_{CC} = V_{O} = 30 V$	Full range			1	μA	
M	Low-level output voltage		25°C		250	400	mV	
V _{OL}		$V_{ID} = -1 V$, $I_{sink} = 4 mA$	Full range			700	mv	
A _{VD}	Large-signal voltage gain	$\label{eq:V_CC+} \begin{array}{l} V_{CC+} = 15 \ V, \ R1 = 15 \ k\Omega, \\ V_O = 1 \ V \ to \ 11 \ V \end{array}$	25°C		200		V/mV	
I _{sink}	Output sink current	$V_{O} = 1.5 \text{ V}, V_{ID} = -1 \text{ V}$	25°C	6	16		mA	
M	Input common-mode		25°C	0		V _{CC+} – 1.5	V	
V _{ICM}	voltage range		Full range	0		$V_{CC+} - 2$	v	
t _{RESP}	Response time ⁽¹⁾	R1 = 5.1 k Ω to V _{CC+} , V _{REF} = 1.4 V	25°C		1.3		μs	
t _{RESP,large}	Large-signal response time	R1 = 5.1 k\Omega to V _{CC+} , V _{REF} = 1.4 V, V _I = TTL	25°C		300		ns	

(1) The response-time specification is for 100-mV input step with 5-mV overdrive. For larger overdrive signals, 300 ns can be obtained.



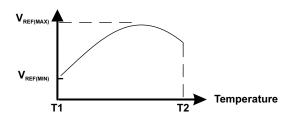
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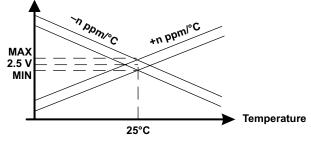
Voltage-Reference Electrical Characteristics

	PARAMETER		TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
V	Reference voltage ⁽¹⁾	TSM102	$V_{KA} = V_{REF}$, $I_K = 10$ mA,	25°C	2.475	2.5	2.525	V
V _{REF}	Reference voltage	TSM102A	See Figure 1	25°C	2.49	2.5	2.51	v
ΔV_{REF}	Reference input voltage deviation over temperature range ⁽¹⁾		$V_{KA} = V_{REF}$, $I_K = 10$ mA, See Figure 1	Full range		7	30	mV
	Average temperature coefficient of reference input voltage ⁽²⁾		$V_{KA} = V_{REF}$, $I_K = 10 \text{ mA}$	Full range		±22	±100	ppm/°C
V _{REF} V _{KA}	Ratio of change in reference voltage to change in cathode voltage		V_{KA} = 3 V to 36 V, I_K = 10 mA, See Figure 2	25°C		-1.1	-2	mV/V
	Defense in terms		I _K = 10 mA, R1 = 10 kΩ, R2 = ∞,	25°C		1.5	2.5	
I _{REF}	Reference input current		See Figure 2	Full range			3	μΑ
ΔI_{REF}	Reference input current deviation over temperature range		I_{K} = 10 mA, R1 = 10 k Ω , R2 = ∞ , See Figure 2	Full range		0.5	1	μΑ
I _{min}	Minimum cathode current for regulation		V _{KA} = V _{REF} , See Figure 1	25°C		0.5	1	mA
I _{K,OFF}	Off-state cathode curren	ıt	See Figure 3	25°C		180	500	nA

(1) ΔV_{REF} is defined as the difference between the maximum and minimum values obtained over the full temperature range.

 $\Delta V_{\text{REF}} = V_{\text{REF}(\text{MAX})} - V_{\text{REF}(\text{MIN})}$ The temperature coefficient is defined as the slopes (positive and negative) of the voltage vs temperature limits within which the (2) reference voltage is specified.

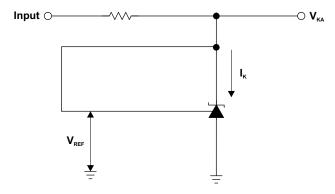




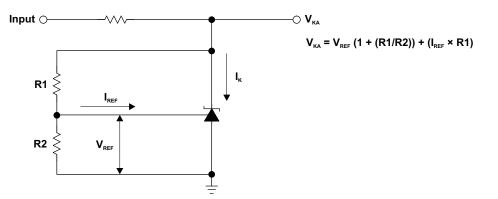


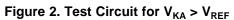


PARAMETER MEASUREMENT INFORMATION









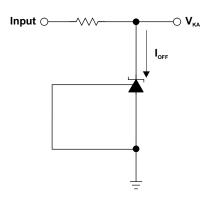


Figure 3. Test Circuit for $I_{\mbox{\scriptsize OFF}}$



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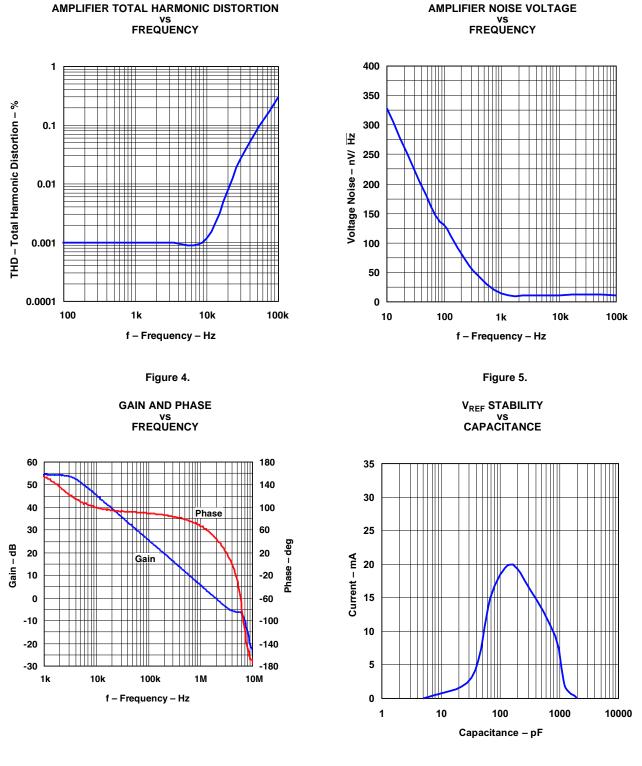
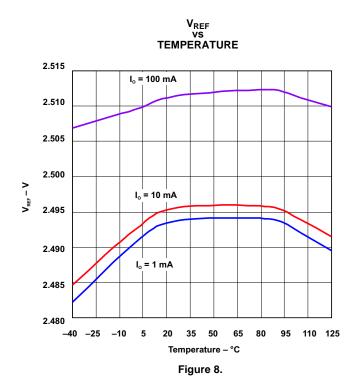


Figure 6.

Figure 7.



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TYPICAL CHARACTERISTICS (continued)



PACKAGE OPTION ADDENDUM

5-Feb-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TSM102AID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102AIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102AIPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102AIPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102IDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TSM102IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

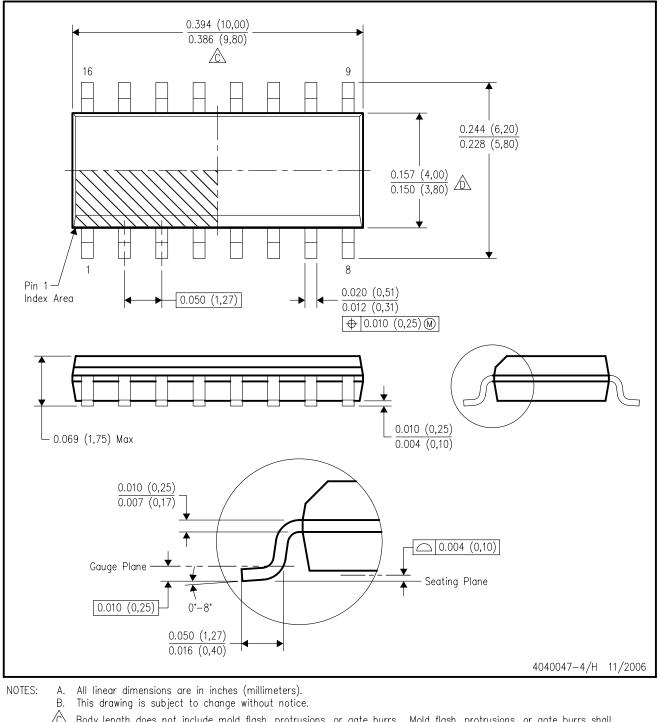
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PLASTIC SMALL-OUTLINE PACKAGE





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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